



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-05-30
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TDA7419TR	JMLR*A140BC6	A	MU1A	2013-05-30
	Amount	UoM	Unit type	ST ECOPACK Grade
	809.00	mg	Each	ECOPACK® 1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	7.5X18X2.5	28	flat	
Comment				

Material Composition Declaration						Mfr Item Name	JMLR*A140BC6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	11.253	mg	supplier	die	Silicon (Si)	7440-21-3		11.086	mg	985160	13703
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	2577	96
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.029	mg	2577	96
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.011	mg	978	14
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.021	mg	1866	26
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.077	mg	6843	95
Leadframe	Copper & its alloys	235.187	mg	supplier	alloy	Copper (Cu)	7440-50-8		229.19	mg	974501	283300
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		5.39	mg	22918	6663
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.325	mg	1382	402
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.282	mg	1199	349
Bonding wire		0.757		supplier	wire	Gold (Au)	7440-57-5		0.757	mg	1000000	936
encapsulation		561.803	mg	supplier	mold compound	Silica, vitreous	60676-86-0		449.443	mg	800001	555554
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		39.326	mg	70000	48611
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		22.472	mg	40000	27778
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		33.708	mg	60000	41666
encapsulation				JIG Table B	mold compound	Antimony Trioxide	1309-64-4		6.742	mg	12001	8334
encapsulation				JIG Table B	mold compound	Brominated Epoxy Resin	40039-93-8		8.427	mg	15000	10417
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		1.685	mg	2999	2083